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2-13-03  
35/I

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/148,723  
Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

**RESPONSE TO NOVEMBER 5, 2002 EX PARTE QUAYLE OFFICE ACTION**

To: Box Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: D. Brent Kenady  
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Responsive to the Office Action dated November 5, 2002, Applicant amends and remarks as follows:

**AMENDMENTS**

**In the Claims**

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 CFR § 1.121(c)(1)(i). Cancel all previous versions of any pending claim.

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